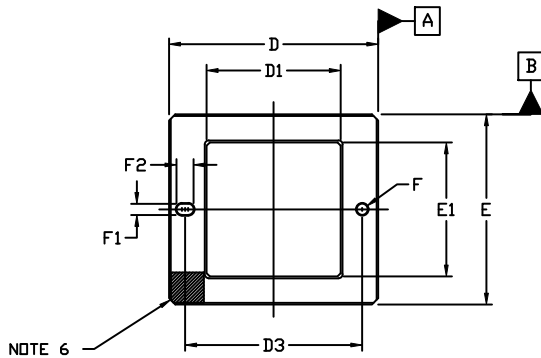


CPGA148, 33x30
CASE 107FK
ISSUE O

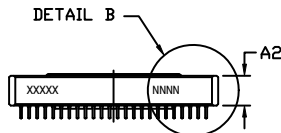
DATE 04 APR 2018

NOTES:

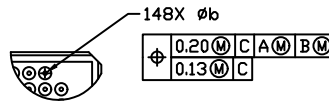
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. THE SEATING PLANE IS DEFINED BY THE OUTER HEATSINK SURFACE.
6. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.



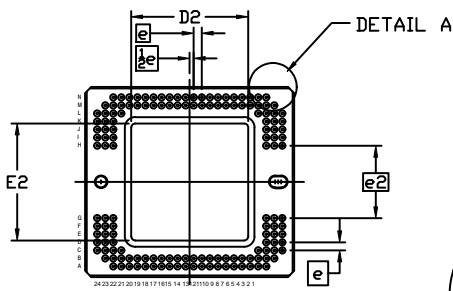
TOP VIEW



SIDE VIEW

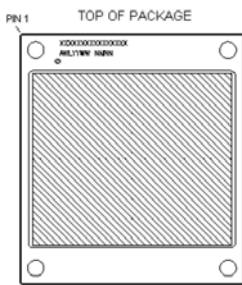


DETAIL A

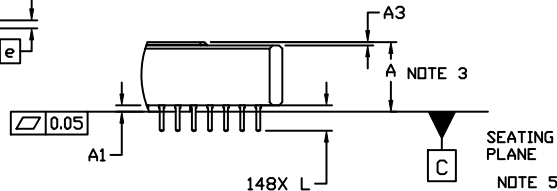


BOTTOM VIEW

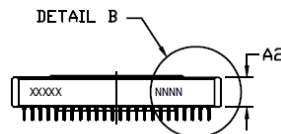
GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week
 NNNN = Serial Number



DETAIL B



SIDE VIEW

XXXX = Specific Device Code
 NNNN = Serial Number

| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN. | NDM. | MAX. |
| A | 5.49 REF | | |
| A1 | 0.45 | 0.50 | 0.55 |
| A2 | 4.24 | 4.72 | 5.20 |
| A3 | 0.27 REF | | |
| b | 0.25 | 0.30 | 0.35 |
| D | 32.67 | 33.00 | 33.33 |
| D1 | 21.05 | 21.13 | 21.21 |
| D2 | 18.34 | 18.44 | 18.54 |
| D3 | 27.66 | 27.94 | 28.22 |
| E | 29.70 | 30.00 | 30.30 |
| E1 | 21.05 | 21.13 | 21.21 |
| E2 | 18.34 | 18.44 | 18.54 |
| e | 1.27 BSC | | |
| e2 | 11.30 | 11.43 | 11.56 |
| F | 1.65 | 1.75 | 1.85 |
| F1 | 1.65 | 1.75 | 1.85 |
| F2 | 2.57 | 2.72 | 2.87 |
| L | 1.80 | 2.00 | 2.20 |

| | | |
|-------------------------|-----------------------|--|
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| DESCRIPTION: | CPGA148, 33x30 | PAGE 1 OF 1 |

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